

RELIABILITY MONITOR

PROCESS: 0.6 μ m Double Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS21352	A4	JUN '01	27346	0103	ATP (Amkor, PI)	DN033071AAA	LQFP	336	77	0
DS21352	A4	JUN '01	27346	0103	ATP (Amkor, PI)	DN033071AAA	LQFP	1000	77	0

TOTALS FOR: 0.6 μ m Double Poly, Double Metal (Ti/TiN layers used on all Metals) FAIL RATE (Fits): 94 DEVICE HRS: 9.72E+06 0

RELIABILITY MONITOR

PROCESS: 0.6 μ m Single Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS80CH11	A4	MAR '01	27058	0103	ATK (Amkor, K)	DN029182AAA	LQFP	48	235	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS80CH11	A4	MAR '01	26786	0103	ATK (Amkor, K)	DN029182AAA	LQFP	336	77	0

TOTALS FOR: 0.6 μ m Single Poly, Double Metal (Ti/Ti) FAIL RATE (Fits): 199 DEVICE HRS: 4.60E+06 0

RELIABILITY MONITOR

PROCESS: 0.6 μ m Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS21Q43	A3-A	DEC '00	26369	0034	ATK (Amkor, K)	DN027568AAC	LQFP	48	234	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS21Q43	A3-A	DEC '00	26370	0034	ATK (Amkor, K)	DN027568AAC	LQFP	336	76	0
DS21Q43	A3-A	DEC '00	26370	0034	ATK (Amkor, K)	DN027568AAC	LQFP	1000	76	0

TOTALS FOR: 0.6 μ m Single Poly, Single Metal FAIL RATE (Fits): 90 DEVICE HRS: 1.02E+07 0

RELIABILITY MONITOR

PROCESS: 0.6 μ m Single Poly, Single Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS5002	C5	JAN '01	26508	0047	ATK (Amkor, K)	DN028766AAD	MQFP	48	198	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2118M	B1	JUN '01	27114	0117	ATK (Amkor, K)	DN101149AAD	SSOP	336	77	0
DS2118M	B1	JUN '01	27114	0117	ATK (Amkor, K)	DN101149AAD	SSOP	1000	77	0
DS2401	C2	SEP '01	27884	0130	Fastech	DA033008AJ	TO92	336	80	0
DS2401	C2	SEP '01	27884	0130	Fastech	DA033008AJ	TO92	1000	80	0
DS5002	C5	APR '01	26901	0112	ATK (Amkor, K)	DN030363AAA	MQFP	336	77	0
DS5002	C6	JUL '01	27364	0122	ATK (Amkor, K)	DN042297AAA	MQFP	336	80	0
DS5002	C5	JAN '01	26509	0047	ATK (Amkor, K)	DN028766AAD	MQFP	336	77	0
DS5002	C5	APR '01	26901	0112	ATK (Amkor, K)	DN030363AAA	MQFP	1000	77	0
DS5002	C6	JUL '01	27364	0122	ATK (Amkor, K)	DN042297AAA	MQFP	1000	80	0
DS5002	C5	JAN '01	26509	0047	ATK (Amkor, K)	DN028766AAD	MQFP	1000	77	0

TOTALS FOR: 0.6 μ m Single Poly, Single Metal (Ti/Ti) FAIL RATE (Fits): 18 DEVICE HRS: 5.13E+07 0

RELIABILITY MONITOR

PROCESS: 0.8 μ m Double Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2154	A2	MAR '01	26762	0106	ATK (Amkor, K)	DN040708AA-	LQFP	48	232	2

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2154	A2	SEP '01	27841	0125	ATK (Amkor, K)	DN104641AA-	LQFP	336	80	0
DS2154	A2	MAR '01	26763	0106	ATK (Amkor, K)	DN040708AA-	LQFP	336	77	0
DS2154	A2	MAR '01	26763	0106	ATK (Amkor, K)	DN040708AA-	LQFP	1000	77	0
DS2154	A2	JUN '01	27101	0107	Stats	DC040702AA-	LQFP	336	77	0
DS2154	A2	JUN '01	27101	0107	Stats	DC040702AA-	LQFP	1000	76	0

TOTALS FOR: 0.8 μ m Double Poly, Double Metal (Ti/T) FAIL RATE (Fits): 128 DEVICE HRS: 2.42E+07 2

RELIABILITY MONITOR

PROCESS: 0.8 μ m Single Poly, Double Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1803	A2	FEB '01	26609	0105	OSEP	DE047362AAB	SOIC	48	232	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1803	A2	MAY '01	26993	0115	Carsem	DM052456AC	SOIC	336	77	0
DS1803	A2	MAY '01	26993	0115	Carsem	DM052456AC	SOIC	1000	76	0
DS1803	A2	FEB '01	26610	0105	OSEP	DE047362AAB	SOIC	336	77	0
DS1803	A2	FEB '01	26610	0105	OSEP	DE047362AAB	SOIC	1000	77	0

TOTALS FOR: 0.8 μ m Single Poly, Double Metal FAIL RATE (Fits): 16 DEVICE HRS: 5.60E+07 0

RELIABILITY MONITOR

PROCESS: 0.8 μ m Single Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR		DATE	ASSEMBLY	LOT NO.	PACKAGE	READ		
		DATE	JOB NO					CODE	FACILITY	POINT
DS1302	A3	MAR '01	26749	0105	CPS (ChipPac, China)	DH036622AB	PDIP	48	234	0
DS1302	A3	DEC '00	26332	0032	CPS (ChipPac, China)	DH028629AB	PDIP	48	234	0
DS1803	A2	FEB '01	26609	0105	OSEP	DE047362AAB	SOIC	48	232	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR		DATE	ASSEMBLY	LOT NO.	PACKAGE	READ		
		DATE	JOB NO					CODE	FACILITY	POINT
DS1302	A3	DEC '00	26333	0032	CPS (ChipPac, China)	DH028629AB	PDIP	336	77	0
DS1302	A3	DEC '00	26333	0032	CPS (ChipPac, China)	DH028629AB	PDIP	1000	77	0
DS1302	A3	MAR '01	26750	0105	CPS (ChipPac, China)	DH036622AB	PDIP	1000	77	0
DS1803	A2	MAY '01	26993	0115	Carsem	DM052456AC	SOIC	336	77	0
DS1803	A2	MAY '01	26993	0115	Carsem	DM052456AC	SOIC	1000	76	0
DS1803	A2	FEB '01	26610	0105	OSEP	DE047362AAB	SOIC	336	77	0
DS1803	A2	FEB '01	26610	0105	OSEP	DE047362AAB	SOIC	1000	77	0

TOTALS FOR: 0.8 μ m Single Poly, Double Metal (Ti/Ti FAIL RATE (Fits): 12 DEVICE HRS: 7.54E+07 0

RELIABILITY MONITOR

PROCESS: 0.8 μ m Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1620	D1	MAR '01	26776	0106	CPS (ChipPac, China)	DH045040AA	SOIC	48	237	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1232	C2-L	JUL '01	27339	0105	ATP (Amkor, PI)	DK046225AB	SOIC	336	80	0
DS1232	C2-L	APR '01	26864	0105	OSEP	DE045054ABB	SOIC	336	77	0
DS1232	C2-L	APR '01	26864	0105	OSEP	DE045054ABB	SOIC	1000	77	0
DS1620	D1	JUN '01	27093	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	336	77	0
DS1620	D1	JUN '01	27093	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	1000	77	0
DS1620	D1	SEP '01	27859	0111	NSEB	DJ051232AAI	SOIC	336	80	0
DS1620	D1	SEP '01	27859	0111	NSEB	DJ051232AAI	SOIC	1000	80	0
DS21S07	C1-	FEB '01	26588	0047	Carsem	DM035532AF	TSSOP	336	77	0
DS21S07	C1-	FEB '01	26588	0047	Carsem	DM035532AF	TSSOP	1000	77	0

TOTALS FOR: 0.8 μ m Single Poly, Single Metal FAIL RATE (Fits): 8 DEVICE HRS: 1.16E+08 0

RELIABILITY MONITOR

PROCESS: 1.2 μ m Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1869	A3	JUN '00	25543	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	48	236	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1233	A5	JUL '01	27352	0110	Carsem	DM048543AA	SOT223	336	68	0
DS1233	A5	APR '01	26871	0101	Fastech	DA048537AF	SOT223	336	77	0
DS1233	A5	OCT '01	28006	0128	Fastech	DA102602AC	SOT223	336	68	0
DS1233	A5	APR '01	26871	0101	Fastech	DA048537AF	SOT223	1000	77	0
DS1267	A1	MAY '01	26979	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	336	75	0
DS1869	A3	JUN '00	25544	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	336	76	0
DS1869	A3	JUN '00	25544	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	1000	75	0

TOTALS FOR: 1.2 μ m Single Poly, Single Metal FAIL RATE (Fits): 12 DEVICE HRS: 7.62E+07 0

RELIABILITY MONITOR

PROCESS: 2.0 μ m Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2175	D1	JAN '01	26422	0046	ATP (Amkor, PI)	DE033119AAB	SOIC	48	233	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2175	D1	JAN '01	26423	0046	ATP (Amkor, PI)	DE033119AAB	SOIC	336	77	0
DS2175	D1	APR '01	26883	0050	ATP (Amkor, PI)	DK036683AB	SOIC	336	77	0
DS2175	D1	JAN '01	26423	0046	ATP (Amkor, PI)	DE033119AAB	SOIC	1000	77	0
DS2175	D1	APR '01	26883	0050	ATP (Amkor, PI)	DK036683AB	SOIC	1000	77	0

TOTALS FOR: 2.0 μ m Single Poly, Single Metal FAIL RATE (Fits): 16 DEVICE HRS: 5.77E+07 0